MA2J1160G

Silicon epitaxial planar type

For switching circuits

■ Features

- Allowing high-density mounting
- Soft recovery characteristic: $t_{rr} = 100 \text{ ns}$

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Maximum peak reverse voltage	V _{RM}	40	V
Forward current (Average)	I _{F(AV)}	100	mA
Peak forward current	I_{FM}	225	mA
Non-repetitive peak forward surge current *	I _{FSM}	500	mA
Junction temperature	Tj	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *: t = 1 s

Package

Code

SMini2-F3

- Pin Name
 - 1: Anode
 - 2: Cathode
- Marking Symbol: 1H

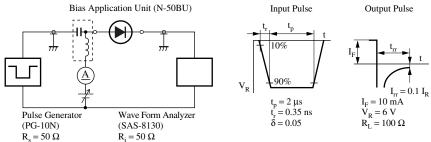
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

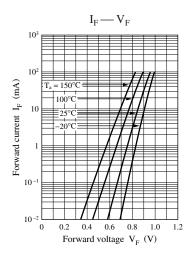
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 100 \text{ mA}$	37 . 1	9	1.2	V
Reverse voltage	V _R	$I_R = 100 \mu A$	35	, VIC	*	V
Reverse current	I _{R1}	V _R = 15 V	0	80.	5	nA
	I_{R2}	$V_R = 40 \text{ V}$	20/	<i>y</i>	10	
	I_{R3}	$V_R = 35 \text{ V}, T_a = 100^{\circ}\text{C}$	1.4		100	μΑ
Terminal capacitance	C _t	$V_R = 6 \text{ V}, f = 1 \text{ MHz}$		1.0	2.0	pF
Forward dynamic resistance *1	$r_{\rm f}$	$I_F = 3 \text{ mA}, f = 30 \text{ MHz}$			3.6	Ω
Reverse recovery time *2	t _{rr}	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			100	ns
		$I_{rr} = 0.1 I_{R}, R_{L} = 100 \Omega$				

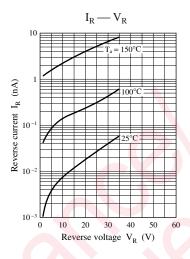
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

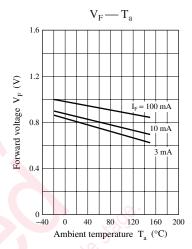
- 2. Absolute frequency of input and output is 10 MHz.
- 3. *1: YHP 4191A RF IMPEDANCE ANALYZER

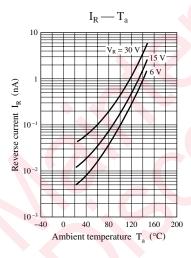
*2: t_{rr} measurement circuit

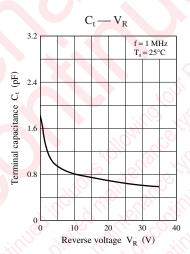






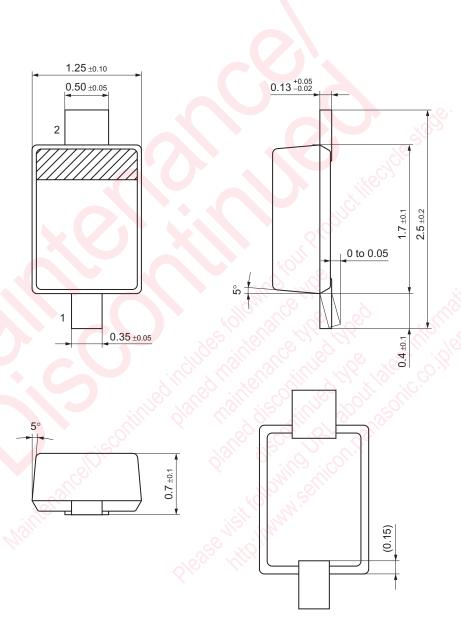






2 SKF00095AED

SMini2-F3 Unit: mm



SKF00095AED 3

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